

MT Thermally Conductive Substrat Polyimide Film

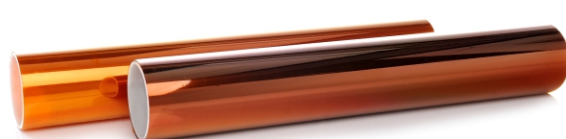
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Q-MANTIC® MT Thermally Conductive Substrat Polyimide Film is a polyimide film possessing high thermal conductivity. Its thermal conductivity properties make it ideal for use in controlling and managing heat in electronic assemblies such as printed circuit boards. When applied to high-density and high-speed operation of microelectronics, it can effectively solve the problems of circuit overheating, stability of components and integrated circuits.

Features

- High temperature resistance
- Excellent thermal conductivity
- Excellent of electrical, chemical and physical property
- Excellent radiation resistance
- Excellent chemical stability



Characteristic

Thickness Nominal (μm)	25	38	43	50
Appearance	Transparent or semi-transparent golden film with smooth and flat surface and without any needle cavities, bubbles or electrically conductive impurities.			
Thickness Tolerance (%)<	±10	±10	±10	±10
Density (kg/cm ³)	1420±20			
Tensile Strength (Mpa)	MD 115 TD 85	MD 100 TD 85	MD 97 TD 86	MD 105 TD 98
Elongation at Rupture(%) ≥	MD 26 TD 27	MD 29 TD 28	MD 30 TD 30	MD16 TD16
Heat Shrinkage 230 °C 1hour (%)<	MD 0.20 TD 0.15	MD 0.20 TD 0.15	MD 0.20 TD 0.15	MD 0.10 TD 0.10
Electrical Strength (kv/mm) ≥	110	110	130	142
Thermal Conductivity (W/m/k) ≥	0.38			

Applications

- Used in circuit boards
- Heat conductive adhesive coating substrate
- Electric heating film
- Power batteries, power supply, UPS, switching power supply
- Smart wear and other industries

Packing

- Min. slitting width: 6mm
- Core ID: 3" / 6"
- Storage: Keep in room temperature. Remove package before use. Unused parts are wrapped in original packaging to avoid moisture absorption. It is recommended to be used up in 6 months.

